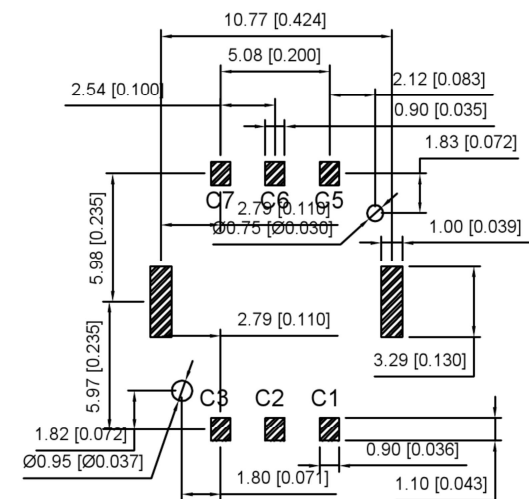
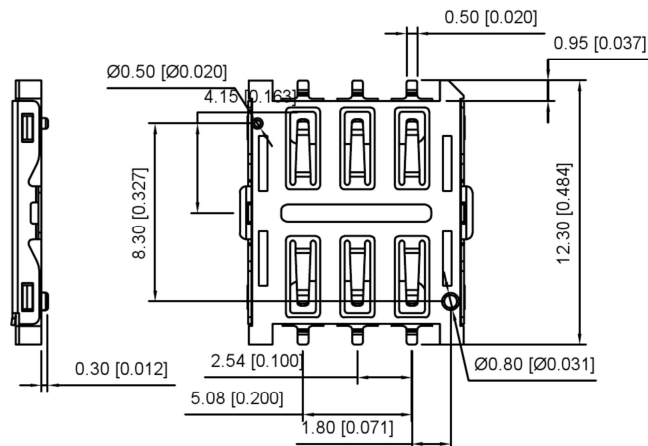
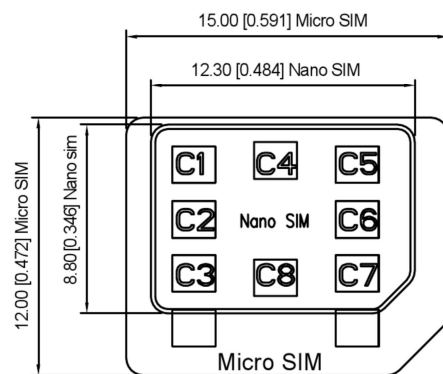
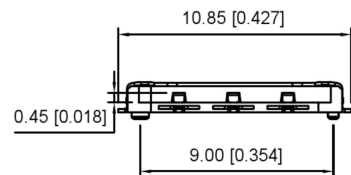
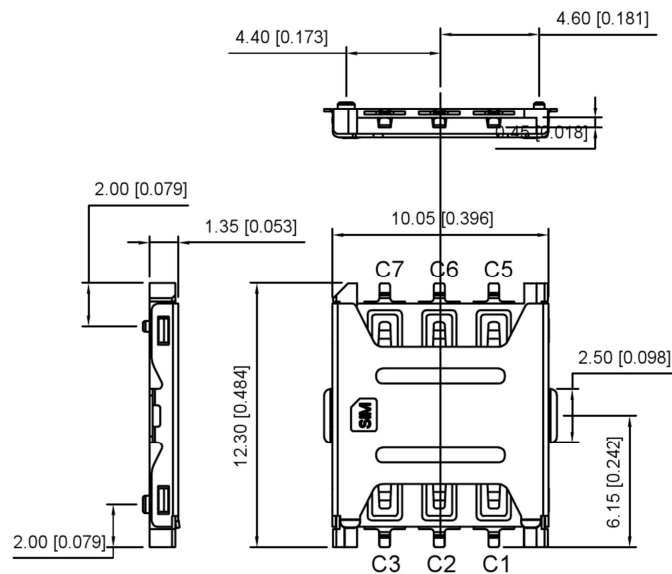
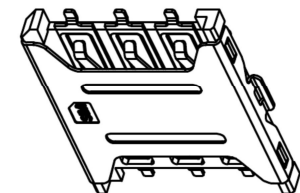




RECOMMEND P.C.B LAYOUT
(General tolerance ± 0.05)



Specification

材料 MATERIAL:

绝缘材料 Insulator: High Temperature Thermoplastic, UL 94V-0.

触点 Contact: C5210

外壳 SHELL: SUS

电镀 PLATING:

触点 Contact: Plated 50u"Ni Overall Contact ALL Au 1U,

外壳 Shell: Plated 50u"Ni Overall, PAD Au 1U

电气 Electrical:

额定电流 Current Rating :0.5mA AC/DC max.

额定电压 Voltage Rating :125V AC/DC

环境温度 Ambient Temperature Range : -20°C+60°C

储存温度 Storage Temperature Range : -40°C+70°C

环境湿度 Ambient Humidity Range :95% R.H. Max.

接触电阻 Contact Resistance:100mΩ max.

绝缘电阻 Insulation Resistance:1000MΩmin./500VDC

无通电寿命 Mating Cycles:10,000 Insertions

回流峰值温度 Reflow peak temp.:260°C $\pm 5^{\circ}\text{C}$, 3~5 S

通电寿命 Mating Cycles:3,000 Insertions Min

SIM pin assignment	
PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出

				ANGLAR	$\pm 5^{\circ}$
				$L \leq 4$	± 0.2
				$4 < L \leq 16$	± 0.3
				$16 < L \leq 63$	± 0.4
				$L > 63$	± 0.5
REVISIONS				UNSPECIFIED TOLERANCES	
www.alpsr.com www.gdxjdz.com www.xbswitch.com					



DONG GUAN XI BANG ELECTRONIC CO., LTD

DSND		SCALE: N/A	MODEL TYPE:
DWN		VIEW:	SIM CARD CONN
CHKD		UNIT: mm/in	PART NO.: XKNANO-1151
APPD		SIZE: A4	DWG NO.:
			WEIGHT
			SHEET
			REVISION
			1/1
			A0